

MA2C029

Silicon epitaxial planar type

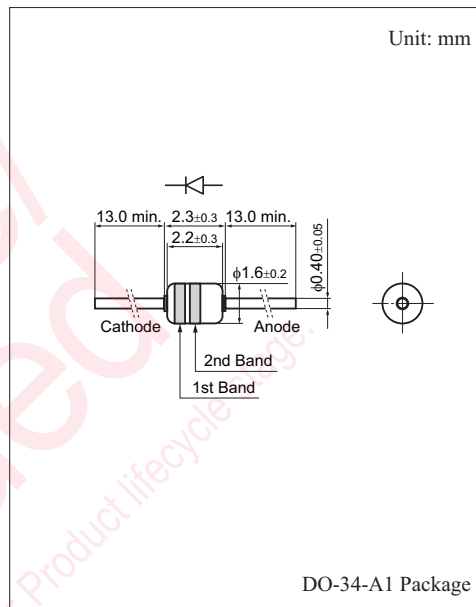
For reduced voltage and temperature compensation

■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Forward current (Average)	$I_{F(AV)}$	50	mA
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}^{*1}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward current	V_{F1}	$I_F = 1.5 \text{ mA}$		2 ^{*2}		V
	V_{F2}	$I_F = 50 \text{ mA}$			1.1	
Reverse current	I_R	$V_R = 6 \text{ V}$			10	μA
Temperature coefficient of forward voltage ^{*3}	$-\Delta V_F / V_T$	$I_F = 1.5 \text{ mA}$		2.0		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25 $^\circ\text{C}$ for V_F measurement. V_F value measured at other temperature must be adjusted to V_F (25 $^\circ\text{C}$)

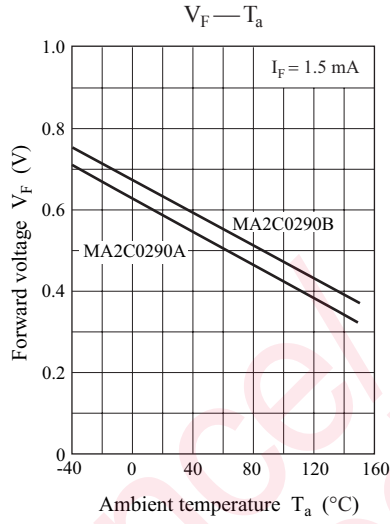
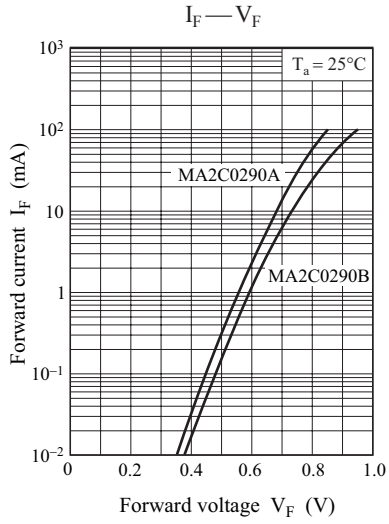
*2:

Type	V_F (V)
MA2C0290A	0.56 to 0.61
MA2C0290A1	0.56 to 0.59
MA2C0290A2	0.58 to 0.61
MA2C0290B	0.59 to 0.64
MA2C0290B1	0.59 to 0.62
MA2C0290B2	0.61 to 0.64

*3: $T_j = 25^\circ\text{C}$ to 150 $^\circ\text{C}$

■ Cathode Indication

Type No.	MA2C0290A	MA2C0290A1	MA2C0290A2	MA2C0290B	MA2C0290B1	MA2C0290B2
1st band color	Red	Red	Red	Blue	Blue	Blue
2nd band color	—	Blue	Yellow	—	Blue	Yellow



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